

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims**

1. (Currently amended) A radio frequency (RF) connector assembly for providing a radio frequency (RF) RF signal path to a chip carrier, said connector assembly comprising:

a body having an inner cylindrical portion and an outer cylindrical portion;

a flange connected to the body and having a cavity that is configured for receiving a chip carrier; and

~~an RF interconnect structure including a plurality of pins extending from the cavity,~~  
~~wherein flange, wherein the cavity of the flange receives a chip carrier and the pins contact the~~  
chip carrier.

2. (Original) The connector assembly according to claim 1, wherein the plurality of pins have a coplanar pin configuration and include at least one signal pin and a ground pin.

3. (Original) The connector assembly according to claim 2, wherein the signal pin is connected to a device in the chip carrier.

4. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein  
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is  
less than 500 mils.

5. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein  
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is  
less than 400 mils.

6. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein  
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is  
less than 300 mils.

7. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein  
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is  
less than 200 mils.

8. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein  
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is  
less than 100 mils.

9. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein  
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is  
less than 75 mils.

10. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein  
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is  
less than 40 mils.

11. (Original) The connector assembly according to claim 1, wherein the cavity receives a substantial portion of the chip carrier.
12. (Original) The connector assembly according to claim 1, wherein the chip carrier is substantially flush with a surface of the flange.
13. (Original) The connector assembly according to claim 1, wherein the cavity is located at a center portion of the flange.
14. (Original) The connector assembly according to claim 13, wherein the cavity is symmetrically centered in the flange.
15. (Original) The connector assembly according to claim 1, wherein the chip carrier includes one of a semiconductor device and an optical driver.
16. (Original) The connector assembly according to claim 1, wherein the plurality of pins have a coplanar pin configuration and include a signal pin and two ground pins, the signal pin being connected to a device in the chip carrier.
17. (Original) The connector assembly according to claim 16, wherein the chip carrier includes a conductive line connecting the signal pin of the connector to the device in the chip carrier.

18. (Original) The connector assembly according to claim 17, wherein the conductive line is coplanar with the signal pin.

19. (Original) The connector assembly according to claim 18, wherein the conductive line is bent prior to contacting the device.

20. (Original) The connector assembly according to claim 17, wherein the conductive line is less than 100 mils.

21. (Original) The connector assembly according to claim 17, wherein the conductive line is less than 50 mils.

22. (New) A radio frequency (RF) connector assembly comprising:  
a cylindrical body;  
a flange extending from a first end of said cylindrical body, said flange comprising a cavity configured for receiving a chip carrier; and  
an RF signal pin extending from the cavity.

23. (New) The RF connector assembly in accordance with claim 22 further comprising:  
means for joining the RF connector assembly to a complimentary connector, wherein said means for joining is adjacent a second of said cylindrical body.

24. (New) The RF connector assembly in accordance with claim 23, wherein said means for joining the RF connector assembly is a threaded structure and rotatable relative to said

cylindrical body.

25. (New) The RF connector assembly in accordance with claim 22, wherein the cavity is coaxially positioned relative to said RF connector assembly.

26. (New) The RF connector assembly in accordance with claim 22 further comprising:  
a plurality of pins, wherein at least said RF signal pin connects to the chip carrier.

27. (New) The RF connector assembly in accordance with claim 26, wherein the plurality of pins are coplanar.

28. (New) A radio frequency (RF) connector assembly comprising:  
a body portion;  
a mounting means adjacent to a first end of said body portion, said mounting means comprising a cavity configured for receiving a chip carrier;  
an RF signal pin extending from the cavity;  
joining means, adjacent a second end of said body portion, for connecting said RF connector assembly to a complimentary connector.

29. (New) The RF connector assembly in accordance with claim 28, wherein said mounting means is a flange.

30. (New) The RF connector assembly in accordance with claim 28, wherein said means for joining said RF connector assembly is a threaded structure and rotatable relative to said body

portion.

31. (New) The RF connector assembly in accordance with claim 28, wherein the cavity is coaxially positioned relative to said RF connector assembly.

32. (New) The RF connector assembly in accordance with claim 28 further comprising:  
a plurality of pins, wherein at least said RF signal pin connects to the chip carrier.

33. (New) The RF connector assembly in accordance with claim 32, wherein the plurality of pins are coplanar.